

WHAT IS CLAIMED IS:

1. A conductive composition which is used for a conductor of an electronic component, comprising a metal particle and a metal oxide particle which has an average particle size of 5 to 60 nm and a melting point of 1500°C or higher,
5 wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle.
- 10 2. A conductive composition according to claim 1, further comprising a binder resin and a solvent dissolving the binder resin.
- 15 3. A conductive composition according to claim 1, wherein the average particle size of the metal oxide particle is 1/3 to 1/80 of that of the metal particle.
- 20 4. A conductive composition which is used for a conductor of an electronic component comprising a metal particle and a metal oxide particle which has a BET value of 20 to 200 m²/g and a melting point of 1500°C or higher, wherein a content of the metal oxide particle is 0.1 to 10.0 wt% based on the amount of the metal particle.
- 25 5. A conductive composition according to claim 4, further comprising a binder resin and a solvent dissolving the binder resin.
6. A conductive composition according to claim 4, wherein the BET value of the metal oxide particle is 5 to 200 times that of the metal particle.

7. A ceramic electronic component comprising:
a ceramic substrate; and
a conductive layer which is formed in at least one
of the inside and outside of the ceramic substrate and
comprises a metal particle and a metal oxide particle which
has an average particle size of 5 to 60 nm and a melting
point of 1500°C or higher,

5 wherein a content of the metal oxide particle is 0.1
to 10.0 wt% based on the amount of the metal particle.

10 8. A ceramic electronic component according to claim
7, which comprises a capacitor formed by including the
ceramic substrate and the conductive layer, wherein, in the
conducting layer, the metal particle is at least one kind
selected from nickel and nickel alloys, and the metal oxide
15 particle is an oxide compound comprising at least one kind
of metals selected from magnesium, aluminum, titanium and
zirconium.

20 9. A ceramic electronic component according to claim
7, which comprises a insulator formed by including the
ceramic substrate and the conductive layer, wherein, in the
conducting layer, the metal particle is at least one kind
selected from silver and silver alloys, and the metal oxide
25 particle is an oxide compound comprising at least one kind
of metals selected from magnesium, aluminum, titanium and
zirconium.